

## GaAs pHEMT MMIC 1.5 WATT POWER AMPLIFIER, 24 - 31.5 GHz

### Typical Applications

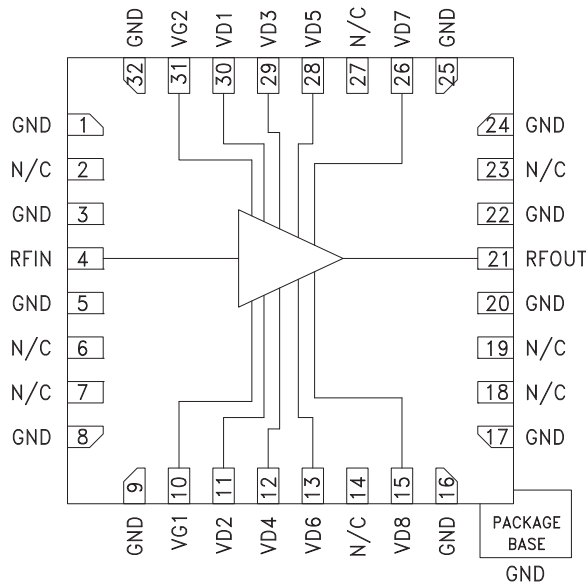
The HMC943LP5E is ideal for:

- Point-to-Point Radios
- Point-to-Multi-Point Radios
- VSAT
- Military & Space

### Features

- Saturated Output Power: +34 dBm @ 24% PAE
- High Output IP3: +41 dBm
- High Gain: 21 dB
- DC Supply: +5.5V @ 1200 mA
- No External Matching Required
- 32 Lead 5x5 mm SMT Package: 25 mm<sup>2</sup>

### Functional Diagram



### General Description

The HMC943LP5E is a four stage GaAs pHEMT MMIC 1.5 Watt Power Amplifier which operates between 24 and 31.5 GHz. The HMC943LP5E provides 22 dB of gain, and +34 dBm of saturated output power and 24% PAE from a +5.5V supply. The high output IP3 of +41 dBm makes the HMC943LP5E ideal for microwave radio applications. The HMC943LP5E amplifier I/Os are internally matched to 50 Ohms and is packaged in a leadless QFN 5x5 mm surface mount package and requires no external matching components.

### Electrical Specifications, $T_A = +25^\circ C$ , $V_{d1} = V_{d8} = +5.5 V$ , $I_{dd} = 1200 mA$ [1]

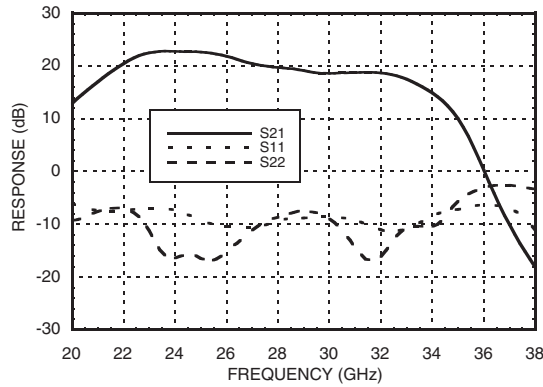
| Parameter   | Min.      | Typ. | Max.        | Min. | Typ.  | Max. | Units  |
|---|-----------|------|-------------|------|-------|------|--------|
| Frequency Range                                   | 24 - 26.5 |      | 26.5 - 31.5 |      |       |      | GHz    |
| Gain  | 18        | 21   |             | 16   | 19    |      | dB     |
| Gain Variation Over Temperature                   |           | 0.03 |             |      | 0.028 |      | dB/ °C |
| Input Return Loss                                 |           | 9    |             |      | 9.5   |      | dB     |
| Output Return Loss                                |           | 12   |             |      | 12    |      | dB     |
| Output Power for 1 dB Compression (P1dB)          | 29        | 32   |             | 27   | 31    |      | dBm    |
| Saturated Output Power (P <sub>sat</sub> )        |           | 33   |             |      | 33    |      | dBm    |
| Output Third Order Intercept (IP3) <sup>[2]</sup> |           | 41   |             |      | 39    |      | dBm    |
| Total Supply Current (I <sub>dd</sub> )           |           | 1200 |             |      | 1200  |      | mA     |

[1] Adjust Vg1 and Vg2 between -2 to 0V to achieve I<sub>dd</sub> = 1200 mA typical.

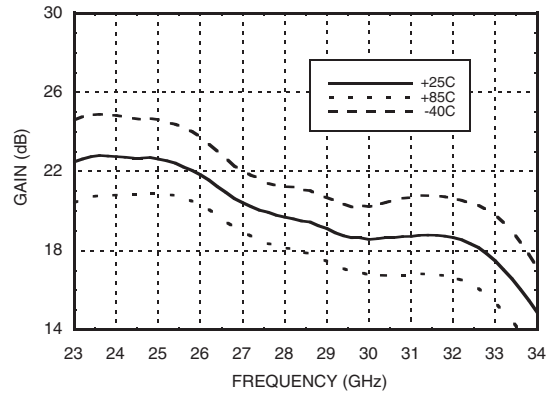
[2] Measurement taken at +5.5V @ 1200 mA, P<sub>out</sub> / Tone = +22 dBm

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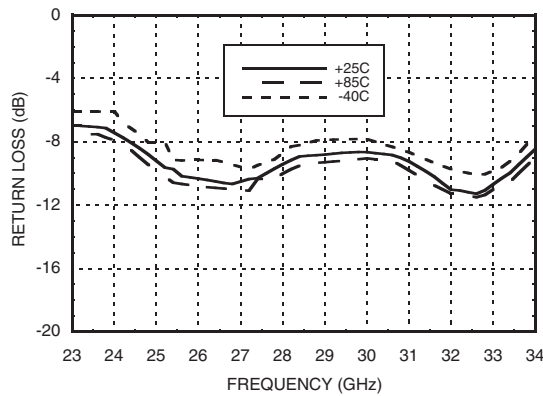
**Broadband Gain &  
Return Loss vs. Frequency**



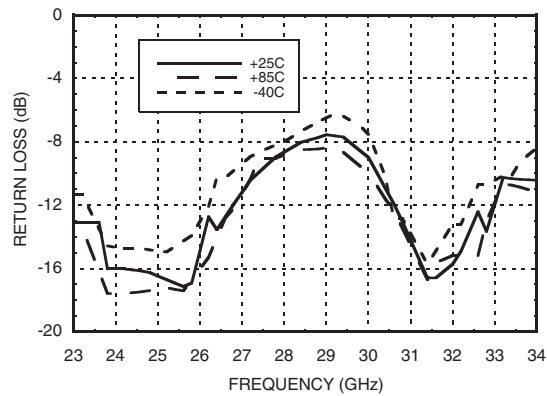
**Gain vs. Temperature**



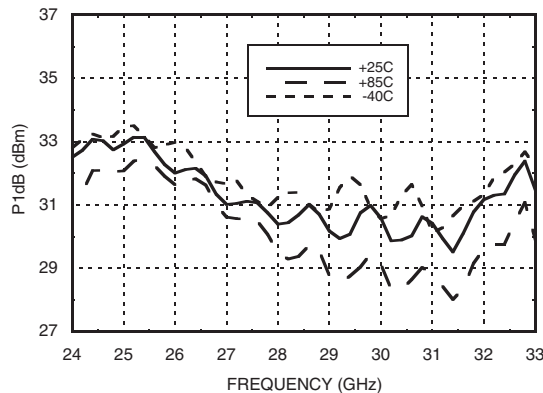
**Input Return Loss vs. Temperature**



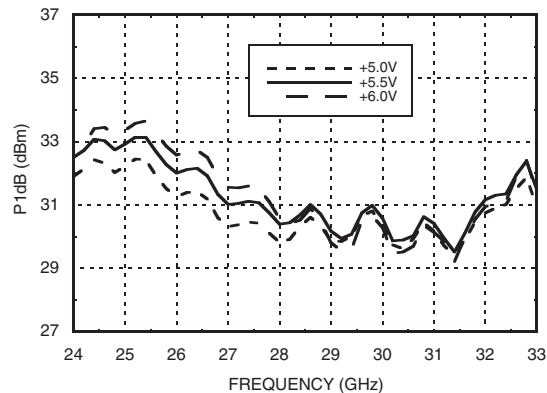
**Output Return Loss vs. Temperature**



**P1dB vs. Temperature**

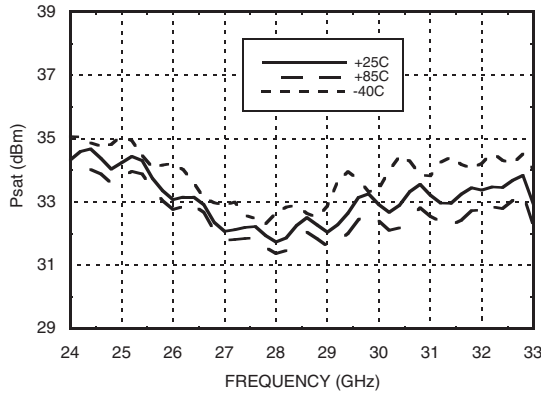


**P1dB vs. Supply Voltage**

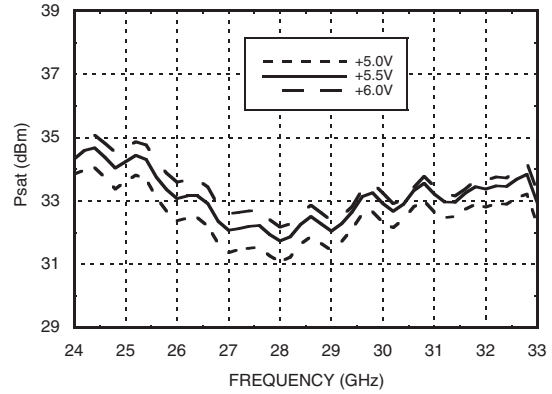


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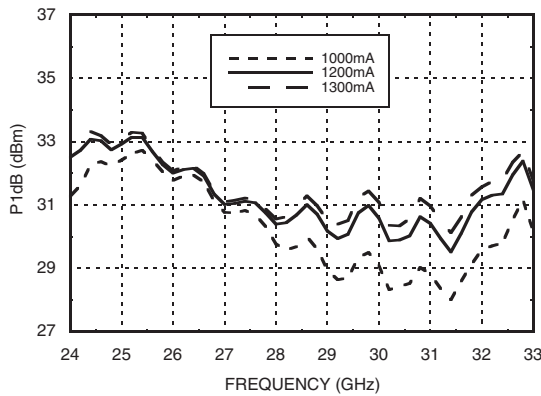
**Psat vs. Temperature**



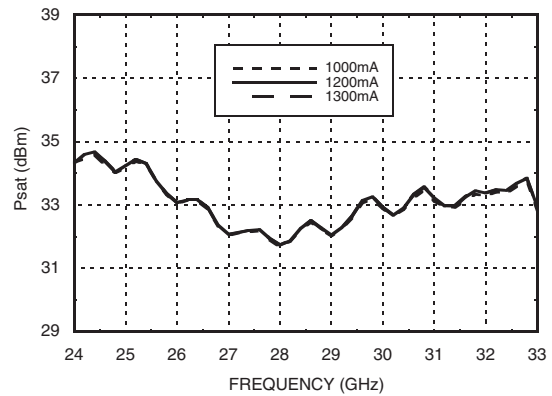
**Psat vs. Supply Voltage**



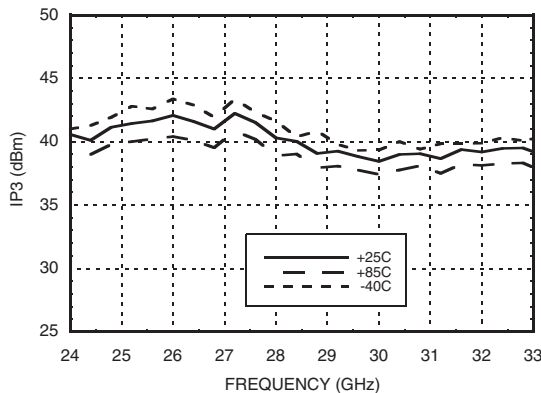
**P1dB vs. Supply Current (Idd)**



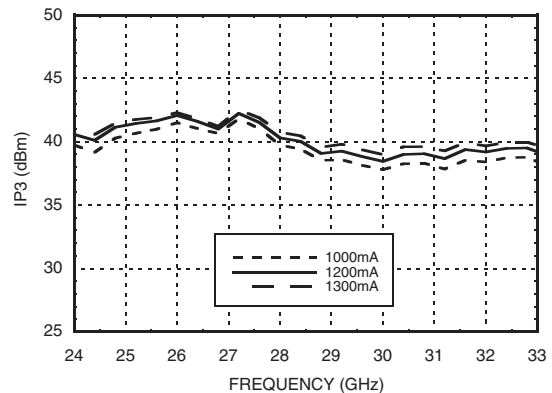
**Psat vs. Supply Current (Idd)**



**Output IP3 vs. Temperature, Pout/Tone = +22 dBm**



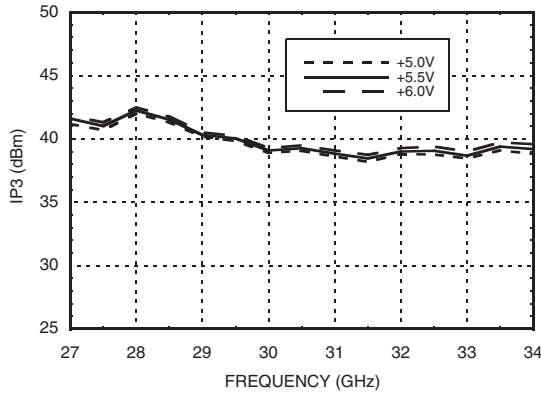
**Output IP3 vs. Supply Current, Pout/Tone = +22 dBm**



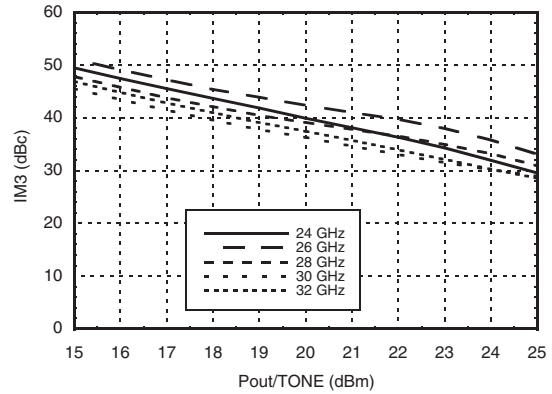


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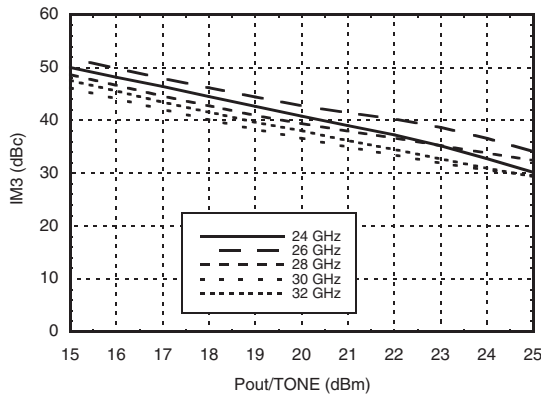
**Output IP3 vs. Supply Voltage, Pout/Tone = +22 dBm**



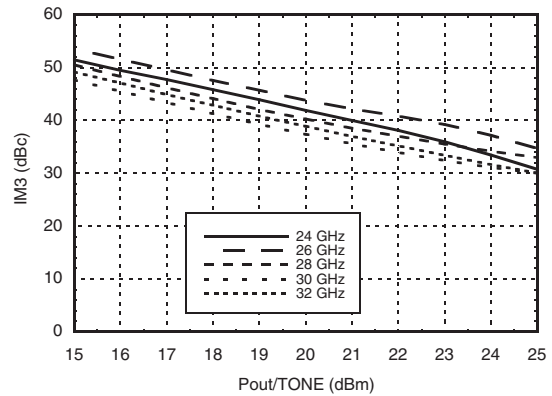
**Output IM3 @ Vdd = +5V**



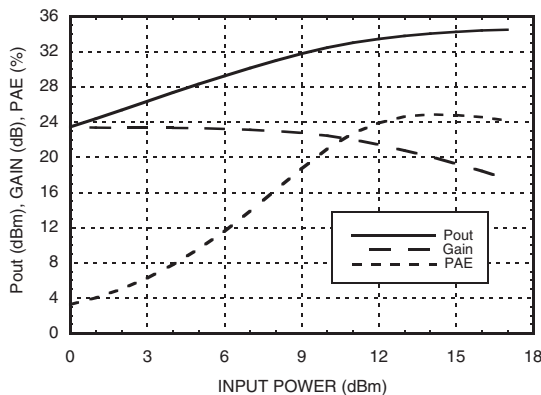
**Output IM3 @ Vdd = +5.5V**



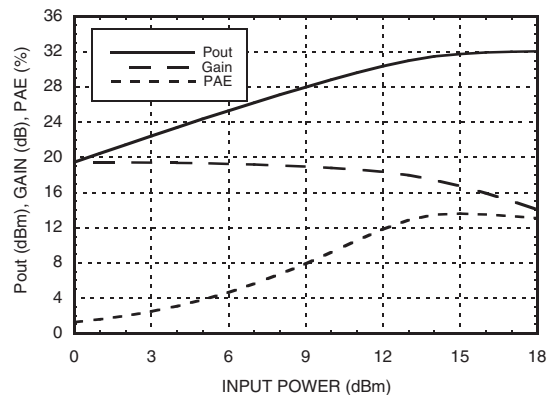
**Output IM3 @ Vdd = +6V**



**Power Compression @ 24 GHz**



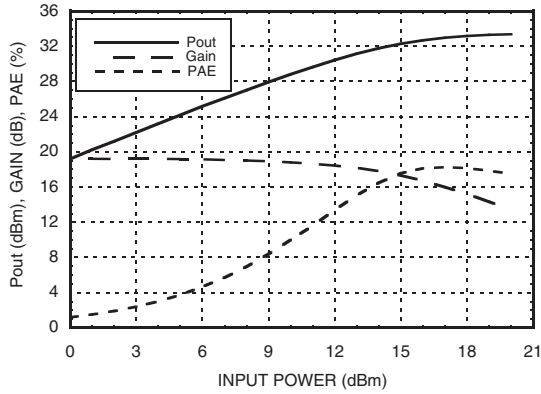
**Power Compression @ 29 GHz**



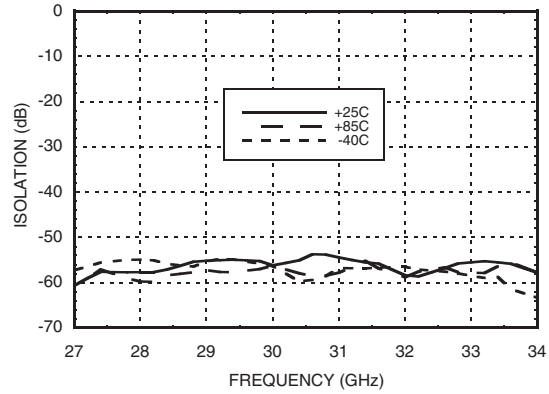


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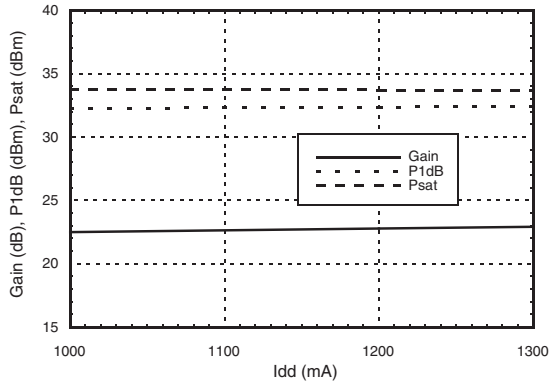
**Power Compression @ 32 GHz**



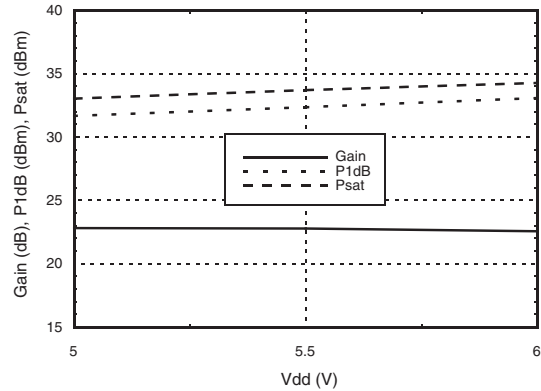
**Reverse Isolation**



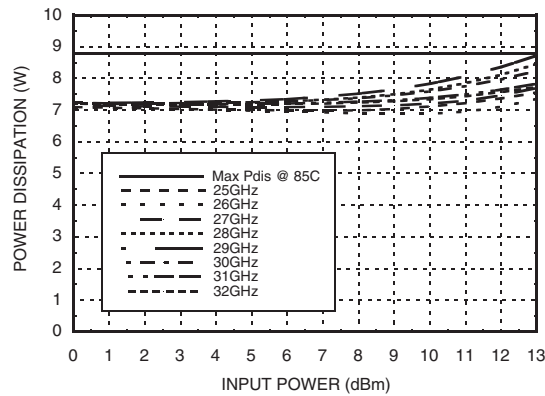
**Gain & Power vs.  
Supply Current @ 26 GHz**



**Gain & Power vs.  
Supply Voltage @ 26 GHz**



**Power Dissipation @ 6V, 1200 mA**



## GaAs pHEMT MMIC 1.5 WATT POWER AMPLIFIER, 24 - 31.5 GHz

### Absolute Maximum Ratings

|   |                |
|---|----------------|
| Drain Bias Voltage (Vd)                                       | +7V            |
| RF Input Power (RFIN)   | +20 dBm        |
| Channel Temperature   | 150 °C         |
| Continuous Pdiss (T= 85 °C)<br>(derate 135 mW/°C above 85 °C) | 8.8 W          |
| Thermal Resistance<br>(channel to package bottom)             | 7.4 °C/W       |
| Storage Temperature   | -65 to +150 °C |
| Operating Temperature   | -55 to +85 °C  |
| ESD Sensitivity (HBM)   | Class 0, 150V  |

### Typical Supply Current vs. Vdd

| Vdd (V) | Idd (mA) |
|---------|----------|
| +5.0    | 1200     |
| +5.5    | 1200     |
| +6.0    | 1200     |

Note: Amplifier will operate over full voltage ranges shown above Vgg adjusted to achieve Idd = 1200mA

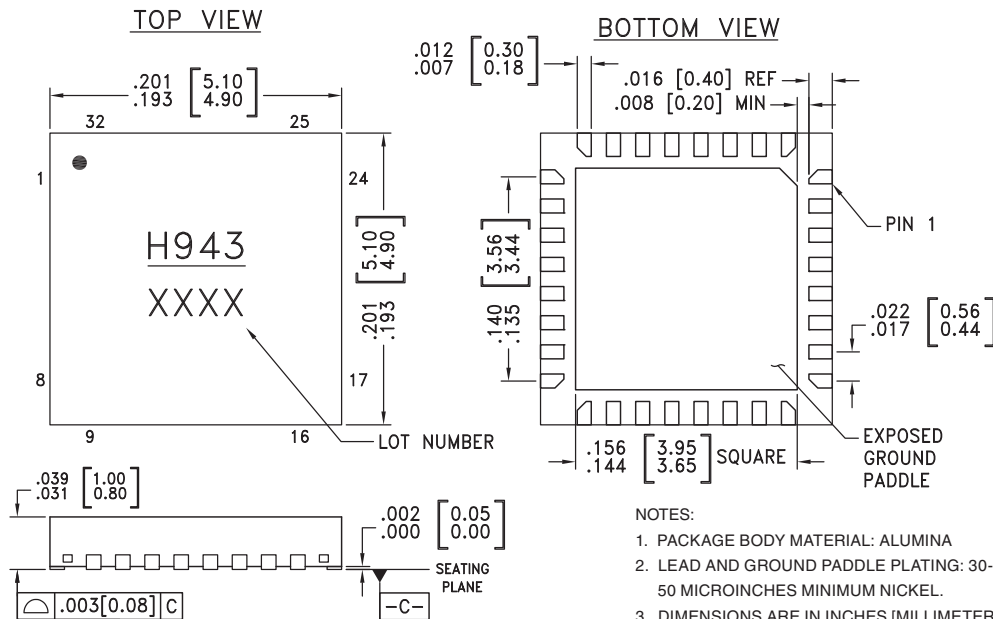


**ELECTROSTATIC SENSITIVE DEVICE  
OBSERVE HANDLING PRECAUTIONS**

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AMPLIFIERS - LINEAR & POWER - SMT

### Outline Drawing



#### NOTES:

1. PACKAGE BODY MATERIAL: ALUMINA
2. LEAD AND GROUND PADDLE PLATING: 30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.
3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM [-C-]
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
7. CLASSIFIED AS MOISTURE SENSITIVITY LEVEL (MSL) 1.

### Package Information

| Part Number | Package Body Material                              | Lead Finish   | MSL Rating          | Package Marking <sup>[1]</sup> |
|-------------|--|---------------|---------------------|--------------------------------|
| HMC943LP5E  | RoHS-compliant Low Stress Injection Molded Plastic | 100% matte Sn | MSL1 <sup>[2]</sup> | H943<br>XXXX                   |

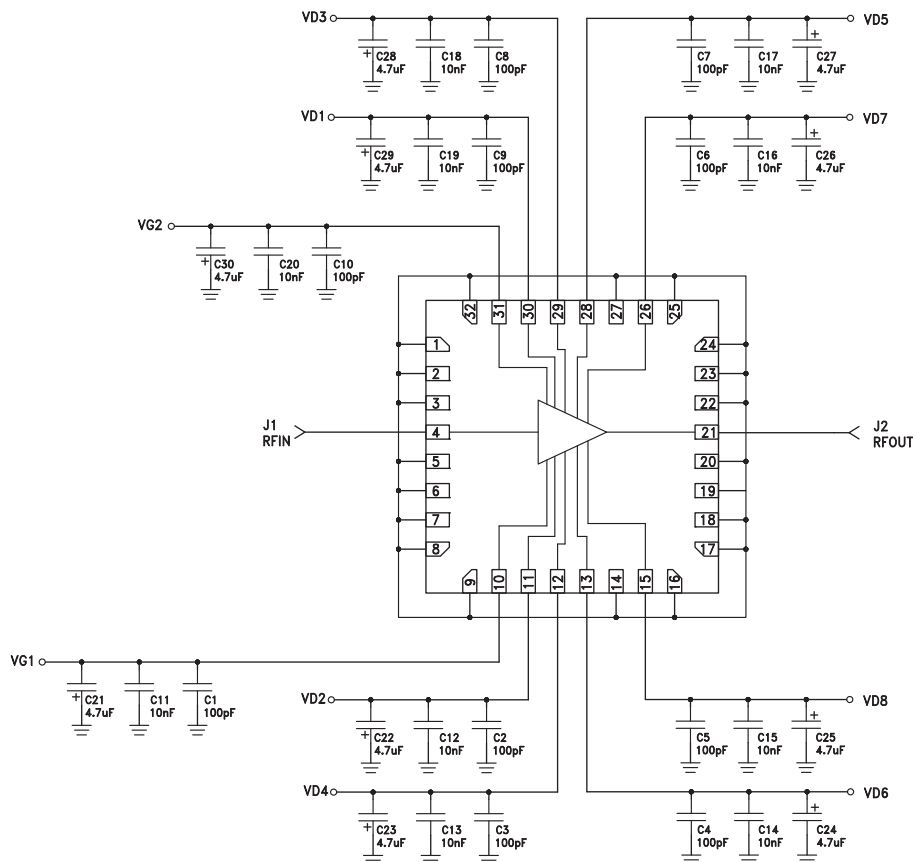
[1] 4-Digit lot number XXXX

[2] Max peak reflow temperature of 260 °C

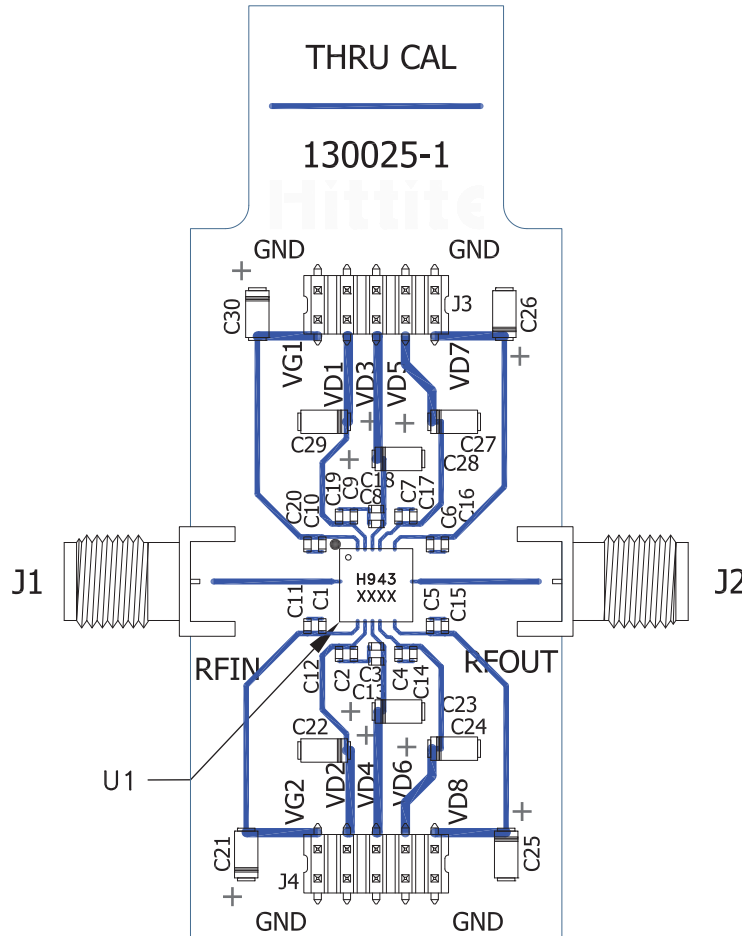
### Pin Descriptions

| Pin Number                                | Function                               | Description  | Interface Schematic |
|---|--|--|---------------------|
| 1, 3, 5, 8, 9, 16, 17, 20, 22, 24, 25, 32 | GND                                    | These pins and package bottom must be connected to RF/DC ground.   |                     |
| 2, 6, 7, 14, 18, 19, 23, 27               | N/C                                    | These pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally. |                     |
| 4   | RFIN                                   | RF signal input. This pad is AC coupled and matched to 50 Ohms over the operating frequency range.   |                     |
| 10, 31                                    | VG1, VG2                               | Gate control for amplifier. External bypass capacitors of 100 pF, 0.01 μF, and 4.7 μF are required on each.                                |                     |
| 11 - 13, 15, 26, 28 - 30                  | VD2, VD4, VD6, VD8, VD7, VD5, VD3, VD1 | Drain bias for the amplifier. External bypass capacitors of 100 pF, 0.01 μF, and 4.7 μF are required on each.                              |                     |
| 21  | RFOUT                                  | RF signal output. This pad is AC coupled and matched to 50 ohms over the operating frequency range.  |                     |

### Application Circuit



**Evaluation PCB**



**List of Materials for Evaluation PCB 130027 [1]**

| Item      | Description                    |
|-----------|--------------------------------|
| J1, J2    | SRI, K Connectors              |
| J3, J4    | DC Pins                        |
| C1 - C10  | 100 pF Capacitors, 0402 Pkg.   |
| C11 - C20 | 10000 pF Capacitors, 0402 Pkg. |
| C21 - C30 | 4.7 μF Capacitors, Case A Pkg. |
| U1        | HMC943LP5E Power Amplifier     |
| PCB [2]   | 130025 Evaluation PCB          |

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350 or Arlon FR4

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.